

ABSTRACT

The present invention relates to a die pad of a leadframe. The die pad is used for receiving a die. The die and the die pad are connected by a solder paste. The die pad comprises a plurality of slots. The slots extend through the die pad. A restrictive region is defined by the slots such that the solder paste is restricted within the restrictive region. The die is positioned on the restrictive region. Because of the cohesion of the solder paste, the solder paste does not flow into the slots. Therefore, the solder paste does not flow and expand everywhere during the heating process. The solder paste is restricted within the restrictive region so that the die on the solder paste does not drift so as to increase the packaging quality.

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